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(54) **Title:** ELECTRICAL BRIDGE PACKAGE WITH INTEGRATED OFF-BRIDGE PHOTONIC CHANNEL INTERFACE

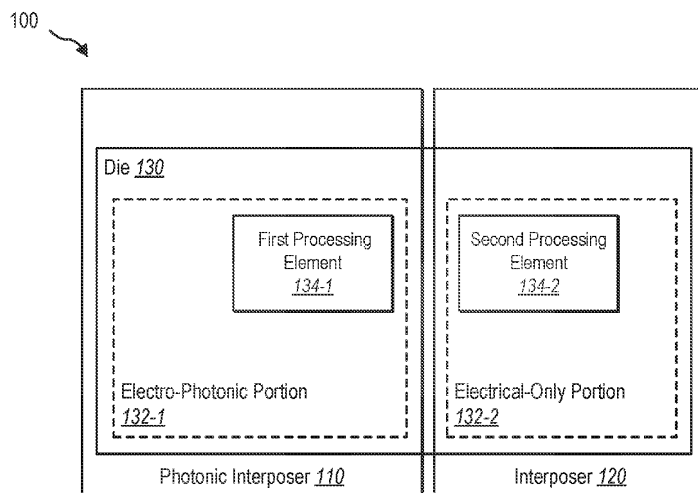


FIG. 1

(57) **Abstract:** A circuit package is described that includes a photonic interposer, a second interposer, and a die partially overlapping and connected to both the photonic interposer and the second interposer.

[Continued on next page]



WO 2024/148373 A1

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